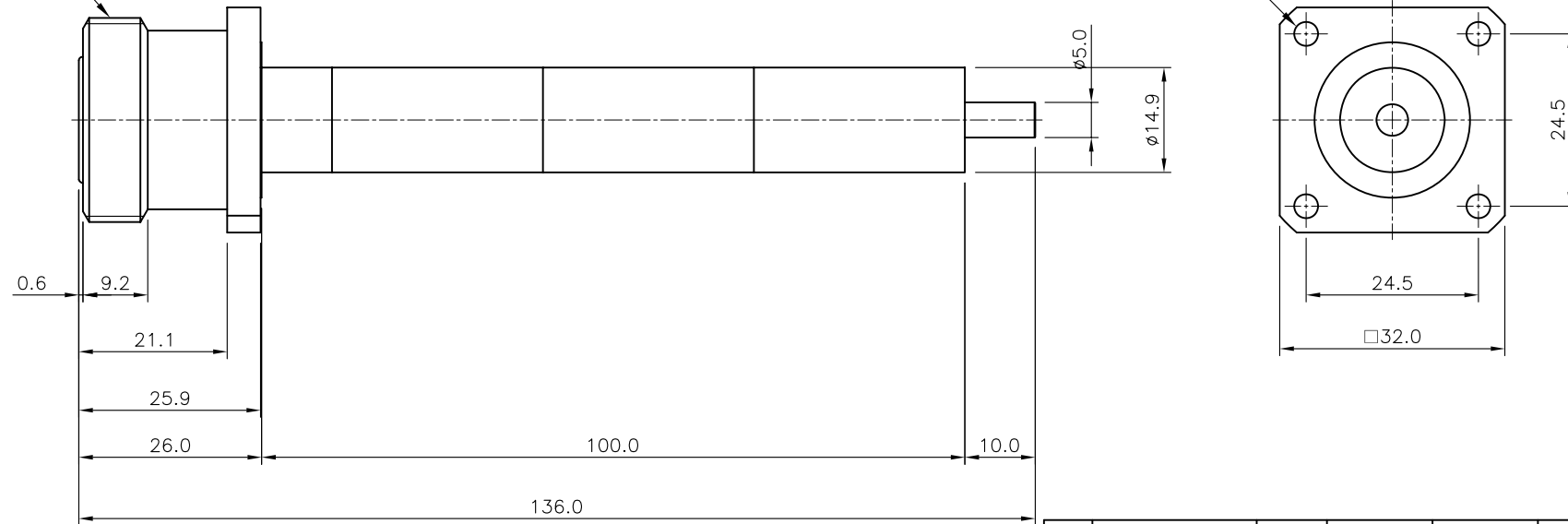


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2013.05.29.
1	[설번처리No.201307-0005] 원가절감 (C-RING변경- PIN 안착부 길이 변경)	E.H.KIM	I.C.KIM	2013.07.12.

M29x1.5

4- ϕ 3.2 THRU



6	SPRING RING	1	BeCu	Silver Plate 7 μ m	DSR01056-5/1
5	INSULATOR	3	TEFLON		DIN02181-N/1
4	INSULATOR	1	TEFLON		DIN02180-N/1
3	CONTACT	1	MBsBD	Silver Plate 3 μ m	DCT02844-5/1
2	CONTACT	1	MBsBD	Silver Plate 3 μ m	DCT02843-5/1
1	BODY	1	MBsBD	SUCO Plate (3 μ m)	DBD03338-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

주 기

1. $\square$ 32 4면 엔드밀 작업시 적용 치수 ($\square$ 32~ $\square$ 31.6)

TOLERANCE	Decimal	DATE 2013. 07. 12.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	-	CHECKED BY		TITLE 7/16 DIN50 SOLDER END JS-4H
		DRAWN BY	E.H.KIM	
FINISH	-	SCALE	1/1	DWG NO. CN02996-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	